

10/696,432

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	355	hydrophobic and (hydrophillic hydrophilic) and @ad<"20020103" and (cmp polish\$3) and slurry and abras\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/27 09:29
L2	7	L1 and tmah	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/27 09:30
L3	74	hydrophobic and (hydrophillic hydrophilic) and @ad<"20020103" and (cmp polish\$3) and slurry and (abras\$3 same micron)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/27 09:53
L4	20	hydrophobic and (hydrophillic hydrophilic) and @ad<"20020103" and (cmp polish\$3) and slurry and (abras\$3 near8 micron)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/27 09:53
S1	10	((("5662769") or ("6165956") or ("5968280") or ("5868863") or ("6207630"))).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/26 21:02
S2	1	S1 and TMAH	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 14:35
S3	0	S1 and TBAH	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 14:35
S4	0	S1 and (tetra adj methyl adj ammonium adj hydroxide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 14:36
S5	0	S1 and (tetra adj butyl adj ammonium adj hydroxide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 14:37
S6	0	S1 and (tetrabutylammonium adj hydroxide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 14:37

S7	1	S1 and (tetramethylammonium adj hydroxide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 14:38
S8	28	((tetramethylammonium adj hydroxide) TMAH) and ((tetrabutylammonium adj hydroxide) TBAH) and @ad<"20020103" and (polish\$3 CMP) and slurry and (tungsten w (silicon adj oxide) sio2 copper cu)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 18:51
S9	2	("5244534").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/22 16:21
S10	28	((tetramethylammonium adj hydroxide) TMAH) and ((tetrabutylammonium adj hydroxide) TBAH) and @ad<"20020103" and (polish\$3 CMP) and slurry and (tungsten w (silicon adj oxide) sio2 copper cu)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:02
S11	28	((tetramethylammonium adj hydroxide) TMAH) and ((tetrabutylammonium adj hydroxide) TBAH) and @ad<"20020103" and (polish\$3 CMP) and slurry and (tungsten w (silicon adj oxide) sio2 copper cu)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 17:02
S12	13	hydrophobic and hydrophilic and @ad<"20020103" and (cmp polish\$3) and slurry and abras\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/26 21:12
S13	355	hydrophobic and (hydrophilic hydrophilic) and @ad<"20020103" and (cmp polish\$3) and slurry and abras\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/27 09:52
S14	0	S13 and tmah and tbah	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/26 21:13
S15	7	S13 and tmah	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/27 09:29